



In the United States Patent and Trademark Office

In re the Application of  
Lee D. Whetsel ✓

Serial No. 09/697,941 ✓

Filed: 10/26/2000 ✓

Title: Integrated Circuit Die With Bypass Bond Pad

TI-20787.2

Art Unit: 2829

Examiner: Nguyen, Vinh P.

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Amendment B Under 37 CFR 1.116

December 20, 2002

Assistant Commissioner  
For Patents  
Washington, D. C. 20231

Dear Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)  
I hereby certify that the above correspondence is  
being deposited with the U.S. Postal Service as  
First Class Mail in an envelope addressed to:  
Assistant Commissioner For Patents, Washington,  
D.C. 20231 on December 20, 2002.  
*Lawrence J. Bassuk*  
Lawrence J. Bassuk, Reg. No. 29,043

*please enter  
01/14/03  
✓*

Responsive to the Examiner's Action of October 18, 2002,  
please amend this application as follows:

**In the Title:**

Amend the title to read as follows:

--Wafer With Die Selector Circuit--

**In the Specification:**

Cancel the existing Abstract and insert a new Abstract as follows:

*B1*

A wafer of semiconductor material is processed to form integrated  
circuit dies. The dies are to be singulated or separated and  
encapsulated for sale and use as integrated circuits. Before



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2002.  
*Lawrence J. Bassuk*  
Lawrence J. Bassuk, Reg. No. 29,043

Dear Sir:

Transmitted herewith is an amendment in this application.

The fee has been calculated as shown below.

CLAIMS AS AMENDED						
	CLAIMS REMAINING AFTER AMENDMENT		HIGHEST NUMBER PREVIOUSLY PAID FOR	PRESENT EXTRA	RATE	ADDITIONAL FEE
Total Claims	10	Minus	32	= 0	x \$18 =	\$ 0
Ind. Claims	2	Minus	10	= 0	x \$84 =	\$ 0
TOTAL ADDITIONAL FEE FOR THIS AMOUNT						\$ 0

Under 37 C.F.R. § 1.16(k) please charge the total additional fee, and any further fees, or credit overpayment to Deposit Account No. 20-0668 of Texas Instruments Incorporated.

Respectfully submitted,

*Lawrence J. Bassuk*

Lawrence J. Bassuk  
Reg. No. 29,043  
Attorney for Applicant

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